Multi-line ESD/EMI Protection for Color LCD Interfaces

UM4601 DFN8 2.0×2.0

UM4611 DFN8 1.7×1.3

UM8601 DFN16 4.0×1.6

UM8611 DFN16 3.3×1.3

#### **General Description**

The UM4601/UM4611/UM8601/UM8611 is a (L-C) low pass filter array with integrated TVS diodes. It is designed to suppress unwanted EMI signals and provide electrostatic discharge (ESD) protection in portable electronic equipment. This device utilizes solid-state silicon-avalanche technology for superior clamping performance and DC electrical characteristics. They have been optimized for protection of color LCD and camera lines in cellular phones and other portable electronics.

The device consists of identical circuits comprised of TVS diodes for ESD protection, and an inductor - capacitor network for EMI filtering. A typical inductor value of 17nH and a capacitor value of 15pF are used to achieve 24dB minimum attenuation from 800MHz to 2.7GHz. The TVS diodes provide effective suppression of ESD voltages in excess of ±15kV (air discharge) and ±8kV (contact discharge) per IEC 61000-4-2, level 4.

The UM4601 is in a RoHS compliant DFN8  $2.0\times2.0$  package, the UM4611 is in a RoHS compliant DFN8  $1.7\times1.3$  package, the UM8601 is in a RoHS compliant DFN16  $4.0\times1.6$  package and the UM8611 is in a RoHS compliant DFN16  $3.3\times1.3$  package. The leads are finished with lead-free. The small package makes it ideal for use in portable electronics such as cell phones, digital still cameras, and PDAs.

#### **Applications**

- Color LCD Protection
- Cell Phone CCD Camera Lines
- Clamshell Cell Phones

#### **Features**

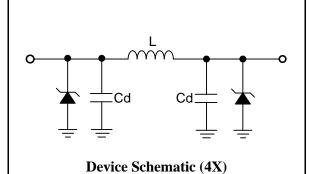
- Bidirectional EMI Filter with Integrated TVS for ESD Protection
- ESD Protection to IEC 61000-4-2 (ESD) Level 4, ±15kV (Air), ±8kV (Contact)
- Filter Performance: 24dB Minimum Attenuation from 800MHz to 2.7GHz
- TVS Working Voltage: 5V
- Inductor: 17nH (Typical)
- Capacitors: 15pF (Typical at  $V_R=2.5V$ )
- Protection and Filtering for Multi Lines
  - UM4601/4611: Four Lines UM8601/8611: Eight Lines
- Solid-State Technology

#### **Ordering Information**

Part Number	Working Voltage	Packaging Type	Channel	Marking Code	Shipping Qty
UM4601	5.0V	DFN8 2.0×2.0	4	ABA	
UM4611	5.0V	DFN8 1.7×1.3	4	AN	3000pcs/7Inch
UM8601	5.0V	DFN16 4.0×1.6	8	8601	Tape & Reel
UM8611	5.0V	DFN16 3.3×1.3	8	8611	

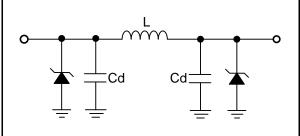
## **Pin Configurations**

**Top View** 



ABA≥

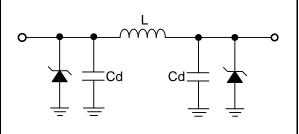
M: Month Code UM4601 DFN8 2.0×2.0



**Device Schematic (4X)** 

AN≥

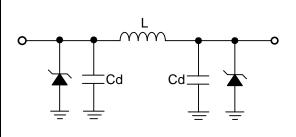
M: Month Code UM4611 DFN8 1.7×1.3



**Device Schematic (8X)** 

8601:XX

XX: Week Code UM8601 DFN16 4.0×1.6



8611:XX

XX: Week Code UM8611 DFN16 3.3×1.3

## **Absolute Maximum Ratings**

Parameter	Symbol	Value	Unit
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	$ m V_{ESD}$	±20 ±15	kV
Junction Temperature	$T_{J}$	125	$\mathcal C$
Operating Temperature Range	$T_{OP}$	-40 to 85	$\mathcal C$
Storage Temperature Range	$T_{STG}$	-55 to 150	$\mathcal C$

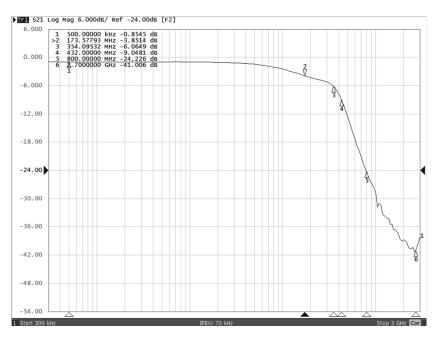
## **Electrical Characteristics**

(T<sub>J</sub>=25 ℃, unless otherwise noted)

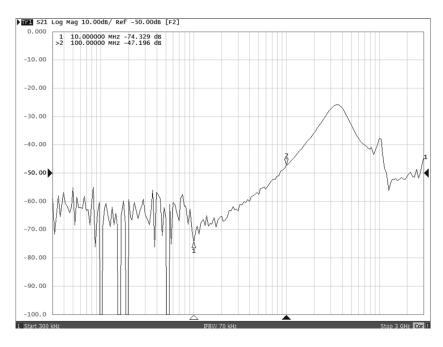
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
TVS Reverse Stand-Off Voltage	$V_{\text{RWM}}$				5	V
TVS Reverse Breakdown Voltage	$V_{BR}$	I <sub>T</sub> =1 mA	6	8	10	V
TVS Reverse Leakage Current	$I_R$	V <sub>RWM</sub> =3.3V			0.1	μΑ
DC Resistance	$R_{cc}$			10		Ω
Roll-Off Frequency at -6dB Attenuation	$f_R$	$Z_{source} = Z_{load} = 50\Omega$		350		MHZ
Filter Cut-Off Frequency	fc	$Z_{\text{source}} = Z_{\text{load}} = 50\Omega$		150		MHZ
Inductance	L			17		nН
Capacitance	$C_d$	$V_R=2.5V$ , $f=1MHZ$		15		pF
Total Capacitance	$C_{total}$	Input to GND, Each Line $V_R=2.5V$ , $f=1MHZ$	24	30	36	pF

## **Typical Operating Characteristics**

### **Typical Insertion Loss**



## **Analog Crosstalk**



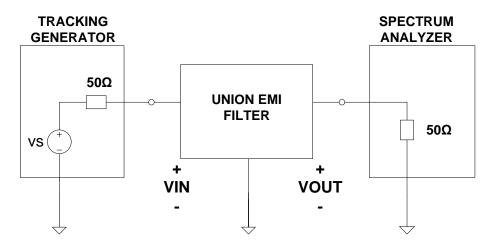
#### **Applications Information**

#### **Insertion Loss**

Insertion Loss (IL) is used to describe the transmission coefficient between two points in a circuit often described in terms of dB. When examining S parameters, S21 is often described as insertion loss. Insertion Loss and S21 will be used interchangeably from here on out. The insertion loss of a circuit with VOUT and VIN would be expressed as

 $IL \!\!=\!\! S_{21}(dB) \!\!=\!\! 20log(V_{OUT}\!/V_{IN}\,)$ 

The setup for measuring insertion loss in a  $50\Omega$  system is shown in the figure below. It will be analyzed in a  $50\Omega$  environment, so the source impedance and load impedance is  $50\Omega$ . The transfer functions then can be analyzed in terms of insertion loss (S21).



Test Conditions: Source Impedance= $50\Omega$ Load Impedance= $50\Omega$ Input Power=0dBm

#### **Cut Off Frequency**

Cut off Frequency is the frequency at which the signal strength is 3.0dB less than it is Pass Band 3.0dB of attenuation equates to half the original signal power. The Pass Band is the range of frequencies that are allowed to "pass" through a filter with minimal attenuation. For our purposes it starts from DC and ends at the cut off frequency.

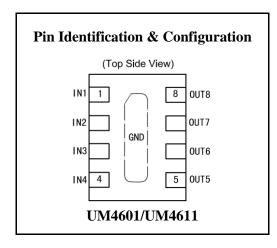
#### **Device Connection**

The UM4601/UM4611/UM8601/UM8611 is comprised of identical circuits consisting of a low pass filter for EMI suppression and dual TVS diodes for ESD protection. The device is in an 8-pin DFN and 16-pin DFN package. Electrical connection is made to all the pins located at the bottom of the device. A center tab serves as the ground connection. The device has a flow through design for easy layout. All path lengths should be kept as short as possible to minimize the effects of parasitic inductance in the board traces.

#### **Ground Connection Recommendation**

Parasitic inductance (L) present in the board layout will affect the filtering performance of the device. As frequency (f) increases, the effect of the inductance becomes more dominant. This effect is given by Equation 1.





Pin	Identification
1-4	Input Lines
5-8	Output Lines
Center Tab	Ground

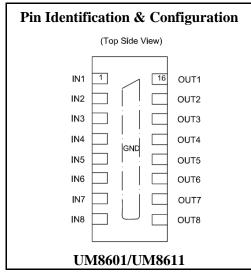
**Equation 1: The Impedance of an Inductor at Frequency XLF** 

$$XLF(L,f) = 2 \times \pi \times f \times L$$

Where:

L= Inductance (H)

f = Frequency (Hz)



Pin	Identification		
1-8	Input Lines		
9-16	Output Lines		
Center Tab	Ground		

**Equation 1: The Impedance of an Inductor at Frequency XLF** 

$$XLF(L, f) = 2 \times_{\pi} \times f \times L$$

Where:

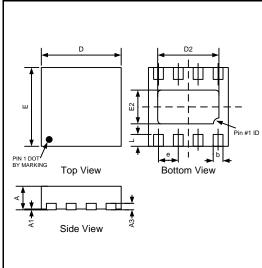
L= Parasitic Inductance in the PCB (H)

f = Frequency (Hz)

## **Package Information**

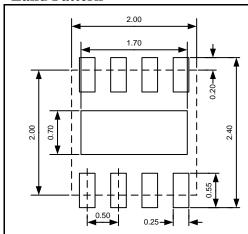
**UM4601: DFN8 2.0×2.0** 

## **Outline Drawing**



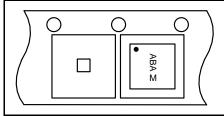
DIMENSIONS							
C11	MILLIMETERS			INCHES			
Symbol	Min	Тур	Max	Min	Тур	Max	
A	0.55	-	0.80	0.022	1	0.031	
A1	0.00	-	0.05	0.000	1	0.002	
A3	0.20REF			0.008REF			
b	0.18	-	0.30	0.007	-	0.012	
D	1.924	2.00	2.076	0.076	0.079	0.082	
D2	1.35	-	1.80	0.053	-	0.071	
Е	1.924	2.00	2.076	0.076	0.079	0.082	
E2	0.75	-	1.00	0.030	-	0.039	
e	0.50TYP			0	.020TY	P	
L	0.20	0.30	0.40	0.008	0.012	0.016	

### **Land Pattern**



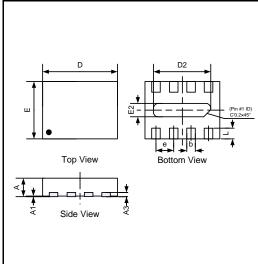
### NOTES:

- 1. Compound dimension: 2.00×2.00;
- 2. Unit: mm;
- 3. General tolerance  $\pm 0.05$ mm unless otherwise specified;
- 4. The layout is just for reference.



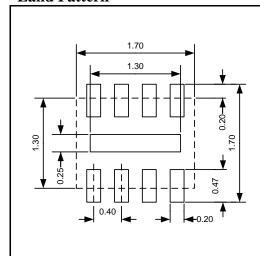
## **UM4611: DFN8 1.7×1.3**

## **Outline Drawing**



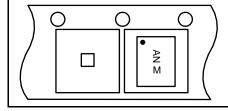
DIMENSIONS								
a	MILLIMETERS			INCHES				
Symbol	Min	Тур	Max	Min	Тур	Max		
A	0.45	0.55	0.60	0.018	0.022	0.024		
A1	0.00	-	0.05	0.000	-	0.002		
A3	(	).15RE	F	0.006REF				
b	0.15	0.20	0.25	0.006	0.008	0.010		
D	1.624	1.70	1.776	0.064	0.067	0.070		
D2	0.85	-	1.40	0.033	-	0.055		
Е	1.25	1.30	1.426	0.049	0.051	0.056		
E2	0.20	-	0.50	0.008	-	0.020		
e	0.40TYP			0	0.016TY	P		
L	0.17	-	0.37	0.007	-	0.015		

### **Land Pattern**



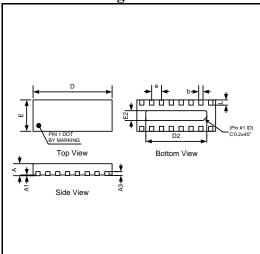
#### NOTES:

- 1. Compound dimension: 1.70×1.30;
- 2. Unit: mm;
- 3.General tolerance ±0.05mm unless otherwise specified;
- 4. The layout is just for reference.



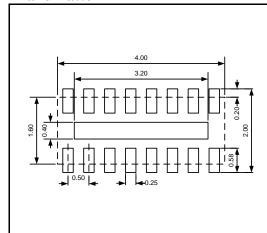
UM8601: DFN16 4.0×1.6

## **Outline Drawing**



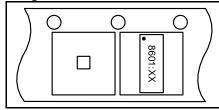
DIMENSIONS								
G11	MILLIMETERS			INCHES				
Symbol	Min	Тур	Max	Min	Тур	Max		
A	0.50	-	0.80	0.020	-	0.031		
A1	0.00	-	0.05	0.000	-	0.002		
A3	0.203REF			0.008REF				
b	0.15	-	0.30	0.006	-	0.012		
D	3.924	4.00	4.076	0.154	0.157	0.160		
D2	2.95	-	3.30	0.116	-	0.130		
Е	1.524	1.60	1.676	0.060	0.063	0.066		
E2	0.30	-	0.60	0.012	-	0.024		
e	0.50TYP			C	.020TY	P		
L	0.15	-	0.38	0.006	-	0.015		

### **Land Pattern**



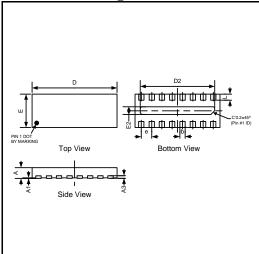
#### NOTES:

- 1. Compound dimension: 4.00×1.60;
- 2. Unit: mm;
- 3. General tolerance  $\pm 0.05$ mm unless otherwise specified;
- 4. The layout is just for reference.



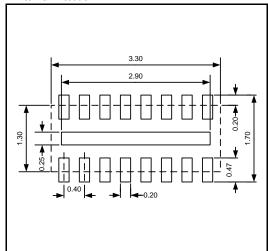
## UM8611: DFN16 3.3×1.3

## **Outline Drawing**



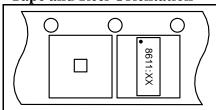
DIMENSIONS								
Cb cl	MILLIMETERS			INCHES				
Symbol	Min	Тур	Max	Min	Тур	Max		
A	0.47	0.55	0.60	0.019	0.022	0.024		
A1	0.00	-	0.05	0.000	-	0.002		
A3	0.15REF			0.006REF				
b	0.15	0.20	0.25	0.006	0.008	0.010		
D	3.224	3.30	3.376	0.127	0.130	0.133		
D2	2.45	-	3.00	0.096	-	0.118		
Е	1.25	1.30	1.426	0.049	0.051	0.056		
E2	0.20	-	0.50	0.008	-	0.020		
e	0.40TYP			C	.016TY	Р		
L	0.17	-	0.37	0.007	-	0.015		

### **Land Pattern**



#### NOTES:

- 1. Compound dimension: 3.30×1.30;
- 2. Unit: mm;
- 3. General tolerance  $\pm 0.05$ mm unless otherwise specified;
- 4. The layout is just for reference.



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